

## PMP10200 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C6	2	22uF	EKXG401ELL220	Panasonic	CAP, AL	18x25mm
C2, C3, C4, C5	4	0.047uF	GRM32DR72J473KW01L	MuRata	CAP, CERM, 0.047 $\mu$ F, 630 V, +/- 10%, X7R,	1210
C7	1	390uF	EEVFK1H391	Panasonic	CAP, AL, 1000 $\mu$ F, 50 V, +/- 20%, 0.073 ohm,	SMT Radial J16
C8	1	DNP	DNP	Panasonic	CAP, AL, 1000 $\mu$ F, 50 V, +/- 20%, 0.073 ohm,	SMT Radial J16
C9	1	DNP	EEV-FK1H102M	Panasonic	CAP, AL, 1000 $\mu$ F, 50 V, +/- 20%, 0.073 ohm,	SMT Radial J16
C10, C101	2	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 $\mu$ F, 50 V, +/- 10%, X7R, 1210	1210
C11	1	0.22uF	GRM21BR71H224KA01L	MuRata	CAP, CERM, 0.22 $\mu$ F, 50 V, +/- 10%, X7R, 0805	0805
C12	1	2.2uF	GCM31CR71H225KA55L	MuRata	CAP, CERM, 2.2 $\mu$ F, 50 V, +/- 10%, X7R,	1206_190
C13	1	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1 $\mu$ F, 50 V, +/- 10%, X7R, 0603	0603
C14, C15	2	DNP	DNP	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%,	0603
D1	1	75V	SMCJ75A	Fairchild Semiconductor	Diode, TVS, Uni, 75 V, 1500 W, SMC	SMC
D2	1	600V	US1J-13-F	Diodes Inc.	Diode, Ultrafast, 600 V, 1 A, SMA	SMA
D3	1	400V	MURS340T3G	ON Semiconductor	Diode, Ultrafast, 400 V, 3 A, SMC	SMC
D4, D5	2	400V	US1G-13-F	Diodes Inc.	Diode, Ultrafast, 400 V, 1 A, SMA	SMA
D6	1	33V	MMSZ5257B-7-F	Diodes Inc.	Diode, Zener, 33 V, 500 mW, SOD-123	SOD-123
D7	1	200V	BAS21-7-F	Diodes Inc.	Diode, Switching, 200 V, 0.2 A, SOT-23	SOT-23
D8	1	15V	SMAZ15	ON Semiconductor	Diode, Zener, 15 V, SMA	SMA
D101	1	18V	MMSZ4705T1G	ON Semiconductor	Diode, Zener, 18 V, 500 mW, SOD-123	SOD-123
F1	1		37214000001	Littelfuse	Fuse, 4 A, 250 V, TH	TR5 fuse 8.5mm DIA
Q1	1	600V	BSS126	Infineon Technologies	MOSFET, N-CH, 600 V, 0.021 A, SOT-23	SOT-23
Q2	1	60V	2N7002-7-F	Diodes Inc.	MOSFET, N-CH, 60 V, 0.17 A, SOT-23	SOT-23
Q3	1	MMBT3904	MMBT3904	Fairchild Semiconductor	Transistor, NPN, 40 V, 0.2 A, SOT-23	SOT-23
Q4	1	800V	STB13N80K5	STMicroelectronics	MOSFET, N-CH, 800 V, DPAK	DPAK
Q5	1	MMBT2907 A	MMBT2907A	Fairchild Semiconductor	Transistor, PNP, 60 V, 0.8 A, SOT-23	SOT-23
R1, R6	2	0	Used in BOM report	Used in BOM report		1210
R2, R3, R4, R7	4	36.5k	CRCW120636K5FKEA	Vishay-Dale	RES, 36.5 k, 1%, 0.25 W, 1206	1206
R5	1	20	CRCW201020R0JNEF	Vishay-Dale	RES, 20, 5%, 0.75 W, 2010	2010
R8, R16	2	DNP	DNP	DNP		0805
R9, R12	2	200k	CRCW0603200KJNEA	Vishay-Dale	RES, 200 k, 5%, 0.1 W, 0603	0603
R10, R19	2	10.0k	CRCW080510K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.125 W, 0805	0805
R11	1	10.0	RC0805FR-0710RL	Yageo America	RES, 10.0, 1%, 0.125 W, 0805	0805
R13, R18	2	22.6k	CRCW060322K6FKEA	Vishay-Dale	RES, 22.6 k, 1%, 0.1 W, 0603	0603
R14	1	5.11k	CRCW08055K11FKEA	Vishay-Dale	RES, 5.11 k, 1%, 0.125 W, 0805	0805
R15	1	499k	CRCW0603499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.1 W, 0603	0603
R17	1	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
R20	1	340	CRCW0603340RFKEA	Vishay-Dale	RES, 340, 1%, 0.1 W, 0603	0603
R21	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
R22	1	7.50k	CRCW06037K50FKEA	Vishay-Dale	RES, 7.50 k, 1%, 0.1 W, 0603	0603

<b>Designator</b>	<b>Quantity</b>	<b>Value</b>	<b>PartNumber</b>	<b>Manufacturer</b>	<b>Description</b>	<b>PackageReference</b>
R23	1	0.39	ERJ-8RQFR39V	Panasonic	RES, 0.39, 1%, 0.25 W, 1206	1206
T1	1	100 uH	750315623	Würth Elektronik	Transformer, 100 uH, SMT	32.31x27.03mm
TP1, TP2, TP3, TP4	4	Double	1503-2	Keystone	Terminal, Turret, TH, Double	Keystone1503-2
U1	1		UCC28700-Q1	Texas Instruments	Constant-Voltage, Constant-Current Controller With Primary-Side	DBV0006A

DNP = DO NOT POPULATE

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